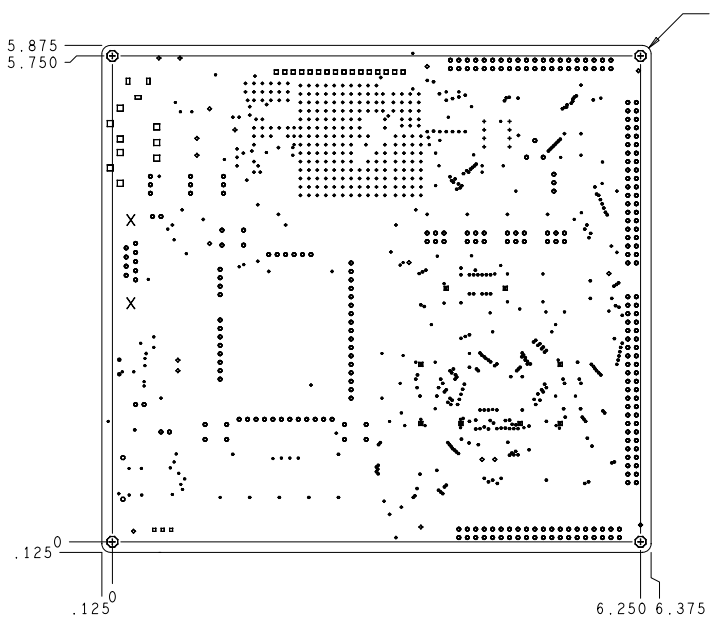
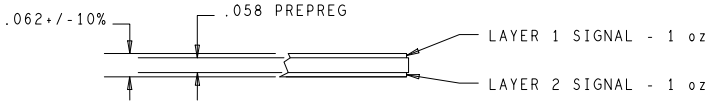


REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
01	ALPHA 1	03/04/08	DFK
02	ALPHA 2	05/27/08	DFK
03	ALPHA 3	07/07/08	DFK
04	BETA 1	11/14/08	DFK
05	BETA 2	04/xx/09	DFK
**	RELEASED TO MANUFACTURING	05/13/09	DFK
*A	CORRECTED RTS, CTS	03/02/11	RKAD



NOTE: 65 MIL 10 MIL SPACING TRACES ON LAYER 1 DIFFERENTIAL IMPEDANCE CONTROLLED TO 90 OHMS +/- 10% TESTED AND CERTIFIED (VENDOR ALLOWED TO ADJUST DIELECTRIC AND LINE WIDTH TO MATCH IMPEDANCE).

DRILL CHART: TOP to BOTTOM ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
•	8.0	+3.0/-8.0	PLATED	265
•	12.0	+3.0/-12.0	PLATED	111
•	18.0	+0.0/-0.0	PLATED	275
•	31.0	+3.0/-3.0	PLATED	8
▫	35.0	+0.0/-0.0	PLATED	3
○	40.0	+3.0/-3.0	PLATED	279
◇	43.0	+3.0/-3.0	PLATED	18
▫	47.0	+3.0/-3.0	PLATED	16
□	70.0	+3.0/-3.0	PLATED	9
X	125.0	+3.0/-3.0	PLATED	2
•	36.0	+3.0/-3.0	NON-PLATED	2
○	44.0	+3.0/-3.0	NON-PLATED	2
■	47.0	+3.0/-3.0	NON-PLATED	8
⊕	125.0	+3.0/-3.0	NON-PLATED	4
▯	70.0x40.0	+3.0/-3.0	PLATED	2
▭	70.0x40.0	+3.0/-3.0	PLATED	1

NOTES:(UNLESS OTHERWISE SPECIFIED)

1. RoHS COMPLIANT CERTIFICATION OR MATERIAL DECLARATION REQUIRED
2. MATERIAL:
   A. IS410 OR EQUIVALENT. MATERIAL MUST CONFORM TO UL94V-0.
   B. USE HTE COPPER, AS SPECIFIED IN THE CROSS SECTION DIAGRAM
   C. OVERALL METAL TO METAL THICKNESS AS SPECIFIED IN THE CROSS SECTION
3. DRILLING:
   A. DIAMETERS IN DRILL TABLE ARE FINISHED HOLE SIZES +/-.003 tol. UNLESS OTHERWISE SPECIFIED IN DRILL TABLE.
   B. TEARDROP ALLOWED ON ENTRY OF VIA ON EVERY TRACE LAYER.
4. PLATING:
   COPPER PLATING IN THRU-HOLES .001 min.
5. MARKING:
   A. SILKSCREEN IN WHITE NON-CONDUCTIVE EPOXY INK ON PRIMARY SIDE OF THE BOARD OR BOTH SIDES IF APPLICABLE.
   B. FABRICATOR TO PLACE DATE CODE AND LOGO ON SECONDARY SIDE IN ETCH (PREFERRED) OR SILKSCREEN.
6. FINAL FABRICATION:
   A. SOLDRMASK PRIMARY AND SECONDARY SIDE OF BOARD USING LIQUID PHOTOIMAGABLE MASK MATERIAL OVER BARE COPPER. PER IPC-SM-840. MASK ARTWORKS PROVIDED ARE 1:1. SOLDERMASK COLOR **BLUE**
7. FINISH:
   A. SHALL BE ELECTROLYTIC NICKEL/GOLD. ELECTROLESS NIKEL / IMMERSION GOLD. (ENIG)
   B. NICKEL THICKNESS: 100-200 MICROINCHES.
   C. GOLD THICKNESS: 3-10 MICROINCHES.
8. BOARDS SHALL BE PURCHASED FROM UL RECOGNIZED VENDORS ONLY AND SHALL BE MARKED IN COPPER ON SECONDARY SIDE OF BOARD WITH VENDORS UL IDENT. FLAMABILITY RATING (94-V0), DATE CODE (WWYY), AND RoHS COMPILANT SYMBOL.
9. MANUFACTURE BOARD TO BE IN ACCORDANCE WITH PERFORMANCE STANDARD IPC-6011/6012 CLASS 2 BOARD TO BE INSPECTED PER IPC-600-A CLASS 2.
10. MAXIMUM WRAP OR TWIST SHALL NOT EXCEED .010 in/in.
11. TESTING:
   A. FABRICATOR TO ADD TEST STRUCTURES OR CUPONS AS NEEDED.
   B. T-LINE IMPEDENCE TO BE TESTED OR GURANTEED WITHIN 10% IF SPECIFIED IN THE CROSS SECTION. TOLERANCE TO BE +/-10% UNLESS OTHERWISE SPECIFIED.

UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE
DIMENSIONS ARE IN INCHES	DRAWN	
TOLERANCES ON; ANGLES +/- 2°	CHECKED RKAD	03/02/11
2 PL DECIMALS +/- .010	ENGRG RKAD	03/02/11
3 PL DECIMALS +/- .005	ISSUED	
THIRD ANGLE PROJECTIONS		

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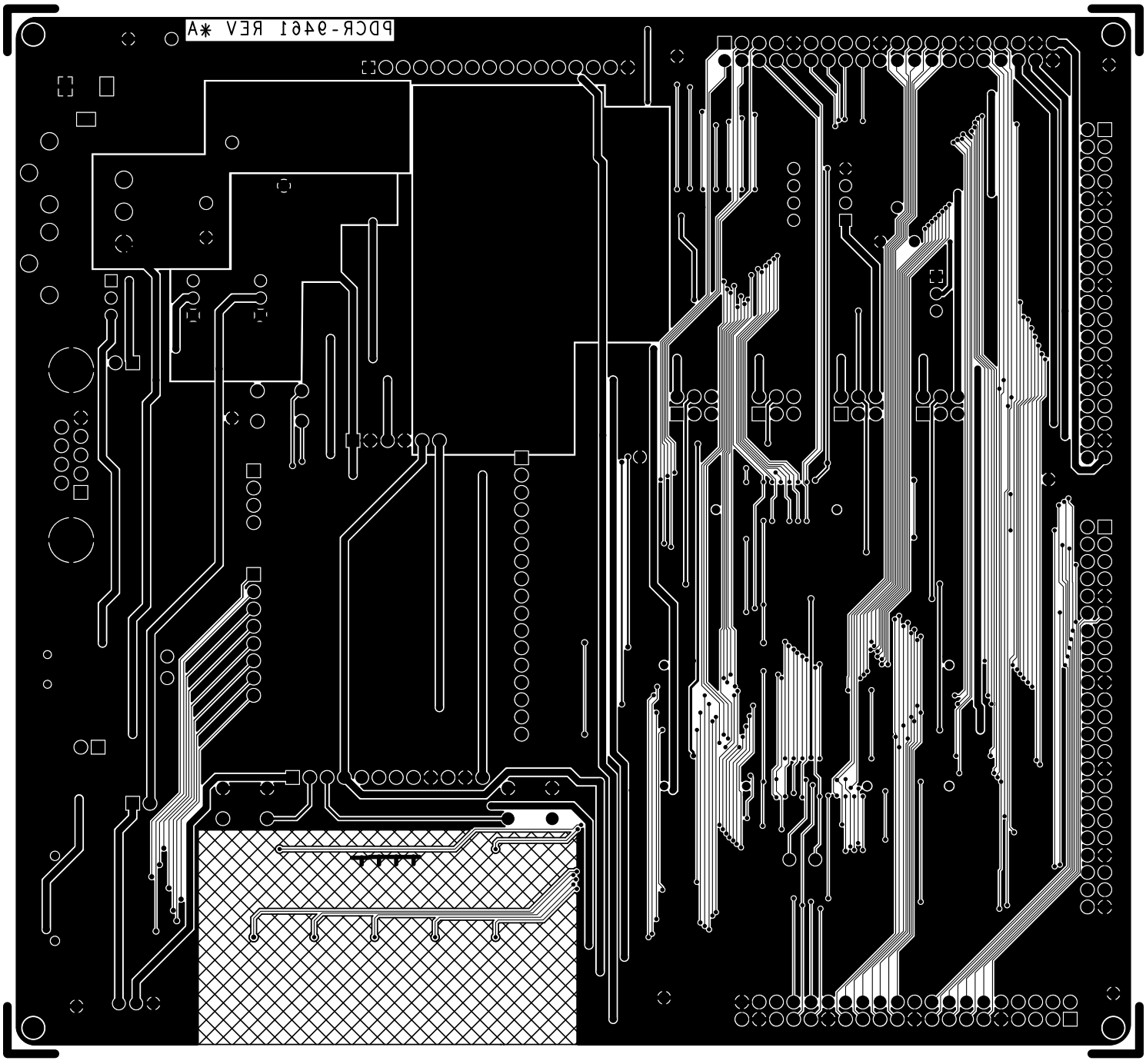
CYPRESS SEMICONDUCTOR

FABRICATION DRAWING
PSoCKit-001
MAIN BOARD

SIZE	FSCM NO	DWG NO	REV
C		PDCR-9461	*A

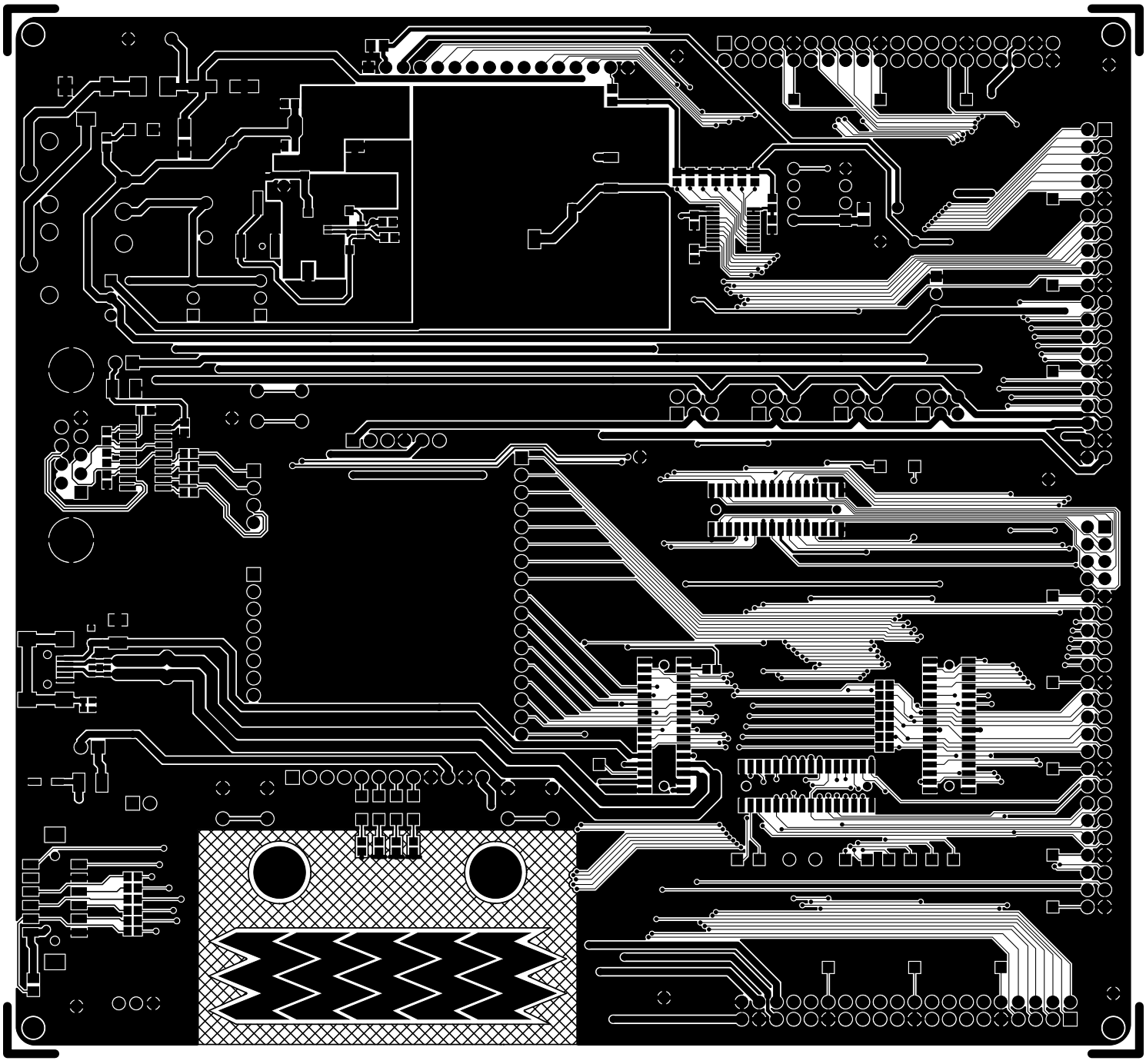
SCALE: 1/1 SHEET:

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PDCR-9461 REV *A SECONDARY SIDE

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PDCR-9461 REV *A PRIMARY SIDE

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